

Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	36.07	36.1	36.13
Insertion Loss	dB	-	26.9	30
1 dB Bandwidth	MHz	7.6	7.65	-
3 dB Bandwidth	MHz	-	7.83	-
40 dB Bandwidth	MHz	-	8.43	8.45
50 dB Bandwidth	MHz	-	8.51	10
Passband Variation	dB	-	0.8	1
Absolute Delay	usec	-	4.9	5
Group Delay Variation($f_0 \pm 3.5\text{MHz}$)	nsec	-	57	100
Ultimate Rejection	dB	50	51	-
Material Temperature coefficient	KHz/°C	-3.3934		
Ambient Temperature	°C	25		
Package Size	DIP3825(38.1x25.4x5.1mm3)			

Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show


Matching Configuration



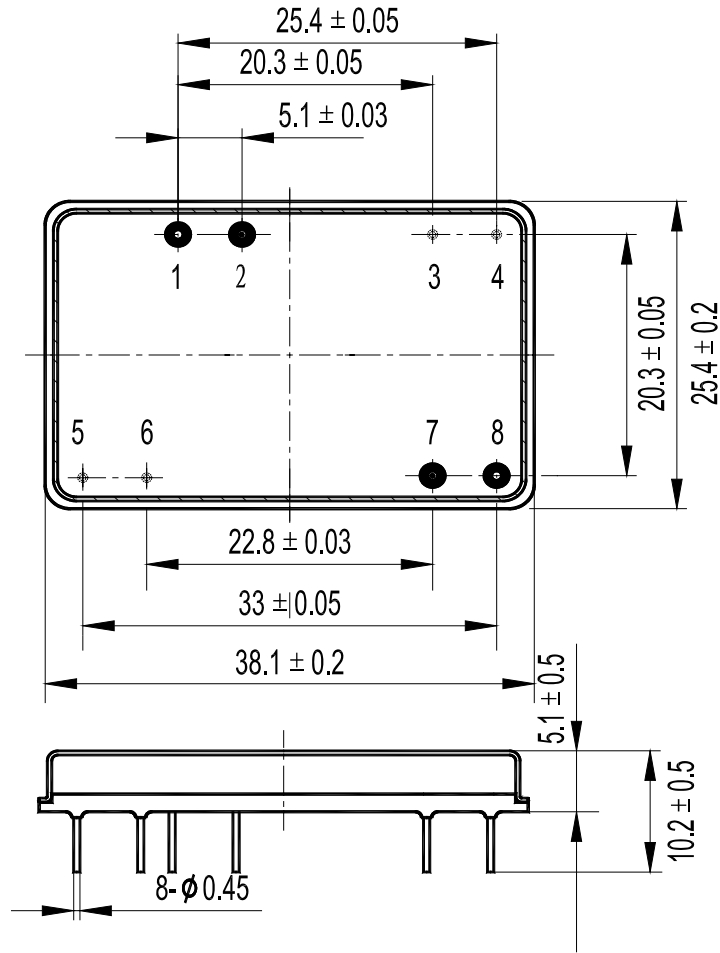
L1=470nH

Source/Load Impedance=50 ohm

Notes - Component values may change depending on board layout.

	SIPAT Co., Ltd. (CETC No. 26 Research Institute) Nanping Huayuan Road No. 14 Chongqing, China, 400060	Part Number	LBN03603	
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Package Dimension



Package:DIP3825

Unit:mm

Input 1
Output 7
Ground 2,3,4,5,6,8

Package: DIP3825

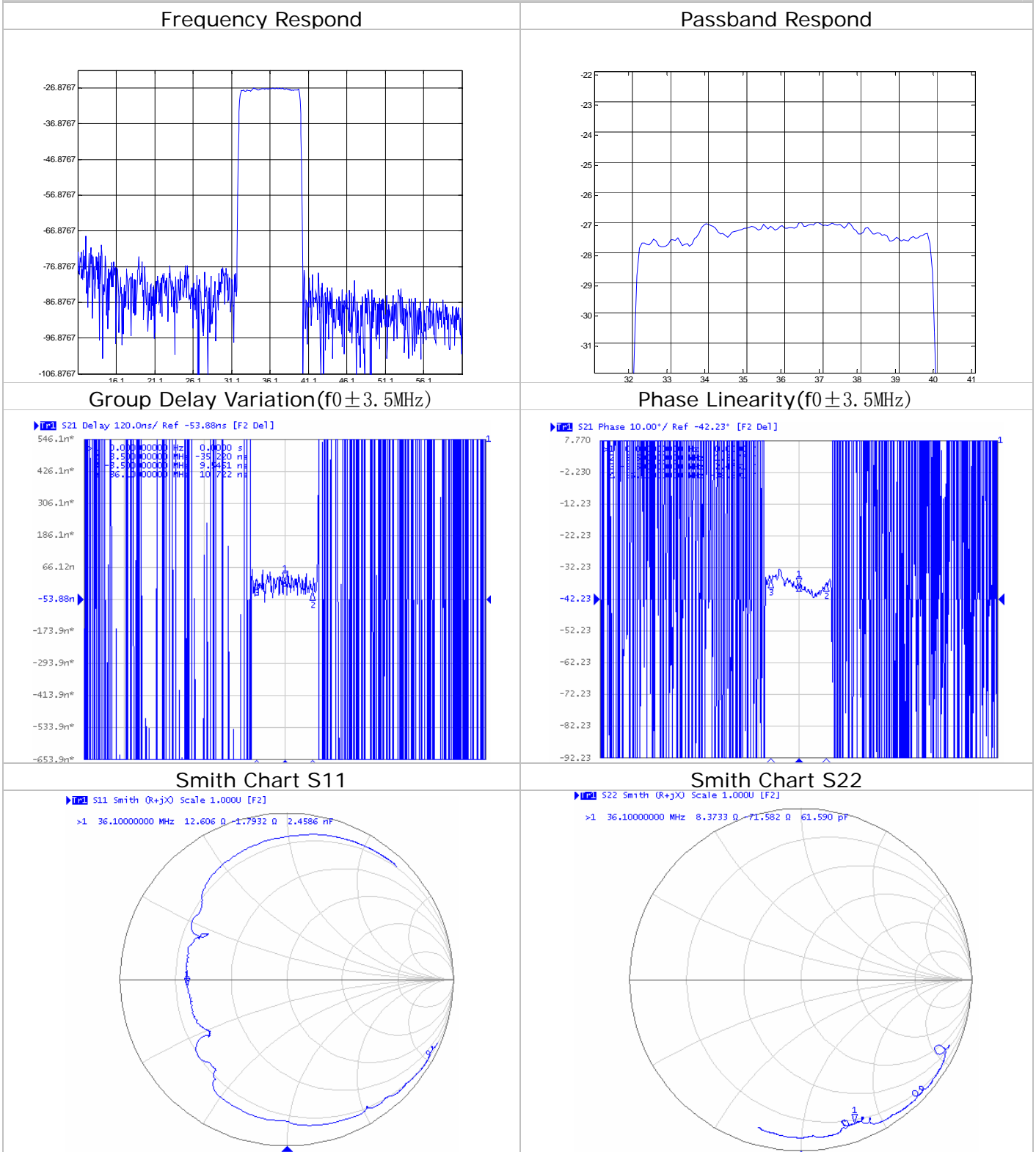
Unit: mm



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Typical Performance



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